

TOSHIBA Field Effect Transistor Silicon N·P Channel MOS Type

HN1L03FU

High Speed Switching Applications
Analog Switch Applications

Q1, Q2 common

• Low threshold voltage

Q1: $V_{th} = 0.8 \sim 2.5 V$ Q2: $V_{th} = -0.5 \sim -1.5 V$

- High speed
- Small package

Q1 Absolute Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit		
Drain-Source voltage	V_{DS}	50	V		
Gate-Source voltage	V _{GSS}	10	V		
Drain current	I _D	50	mA		

Q2 Absolute Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit
Drain-Source voltage	V_{DS}	-20	V
Gate-Source voltage	V _{GSS}	-7	V
Drain current	ID	-50	mA

Absolute Maximum Ratings (Q1, Q2 Common) (Ta = 25°C)

Characteristic	Symbol	Rating	Unit
Drain power dissipation	P _{D*}	200	mW
Channel temperature	T _{ch}	150	°C
Storage temperature range	T _{stg}	-55~150	°C

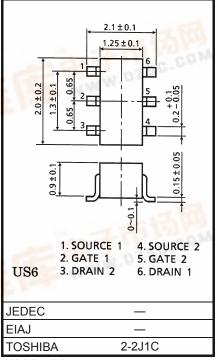
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling

Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

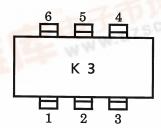
* Total rating



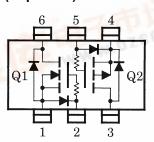


Weight: 6.8mg

Marking



Equivalent Circuit (Top View)





Q1 Electrical Characteristics (Ta = 25°C)

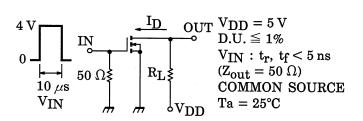
Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = 10V, V _{DS} = 0	_	_	1	μΑ
Drain-Source breakdown voltage		V _{(BR) DSS}	I _D = 100μA, V _{GS} = 0	50	_	_	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 50V, V _{GS} = 0	_	_	1	μΑ
Gate threshold v	oltage	V _{th}	V _{DS} = 5V, I _D = 0.1mA	0.8	_	2.5	V
Forward transfer admittance	•	Y _{fs}	V _{DS} = 5V, I _D = 10mA	20	_	_	mS
Drain-Source ON resistance		R _{DS} (ON)	I _D = 10mA, V _{GS} = 4.0V	_	20	50	Ω
Input capacitance		C _{iss}	V _{DS} = 5V, V _{GS} = 0, f = 1MHz	_	6.3	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 5V, V _{GS} = 0, f = 1MHz	_	1.3	_	pF
Output capacitance		C _{oss}	V _{DS} = 5V, V _{GS} = 0, f = 1MHz	_	5.7	_	pF
Switching time	Turn-on time	t _{on}	V _{DD} = 5V, I _D = 10mA, V _{GS} = 0~4.0V	_	0.11	_	μs
	Turn-off time	t _{off}	V _{DD} = 5V, I _D = 10mA, V _{GS} = 0~4.0V	_	0.15	_	μs

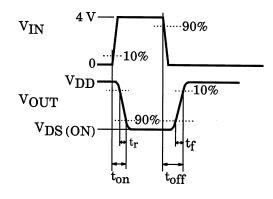
Q2 Electrical Characteristics (Ta = 25°C)

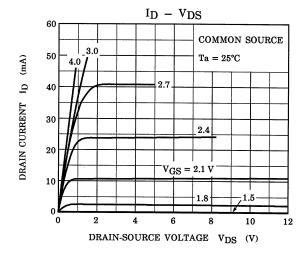
Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = -7V, V _{DS} = 0	_	_	-1	μΑ
Drain-Source breakdown voltage		V _{(BR) DSS}	I _D = -100μA, V _{GS} = 0	-20	_	_	V
Drain cut-off curr	rent	I _{DSS}	V _{DS} = -20V, V _{GS} = 0	_	_	-1	μΑ
Gate threshold v	roltage	V _{th}	V _{DS} = -3V, I _D = -0.1mA	-0.5	_	-1.5	V
Forward transfer	admittance	Y _{fs}	V _{DS} = -3V, I _D = -10mA	15	_	_	mS
Drain-Source ON resistance		R _{DS (ON)}	I _D = -10mA, V _{GS} = -2.5V	_	20	40	Ω
Input capacitance		C _{iss}	$V_{DS} = -3V, V_{GS} = 0,$ f = 1MHz	_	10.4	_	pF
Reverse transfer capacitance		C _{rss}	$V_{DS} = -3V, V_{GS} = 0,$ f = 1MHz	_	2.8	_	pF
Output capacitance		C _{oss}	$V_{DS} = -3V, V_{GS} = 0,$ f = 1MHz	_	8.4	_	pF
Switching time	Turn-on time	t _{on}	V _{DD} = -3V, I _D = -10mA, V _{GS} = 0~-2.5V	_	0.15	_	μs
	Turn-off time	t _{off}	V _{DD} = -3V, I _D = -10mA, V _{GS} = 0~-2.5V	_	0.13	_	μs

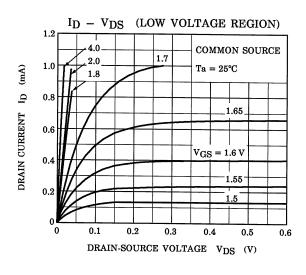
Q1 (Nch MOS FET)

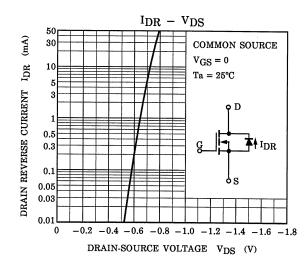
Switching Time Test Circuit

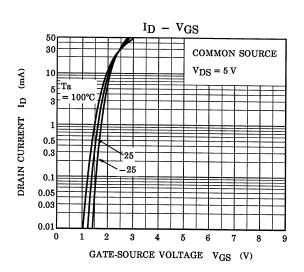






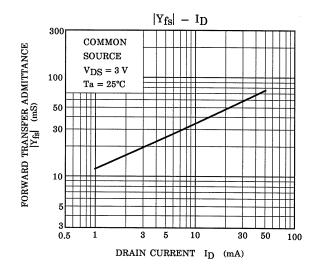


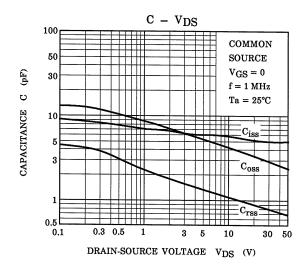


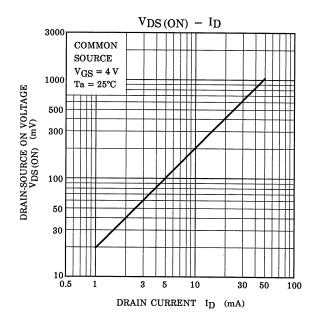


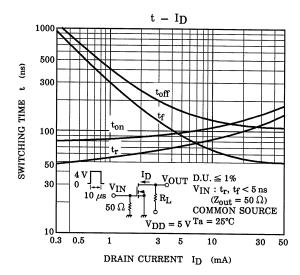
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Q1 (Nch MOS FET)



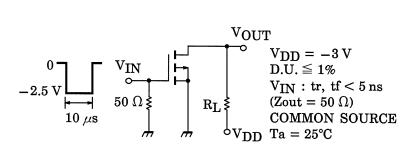


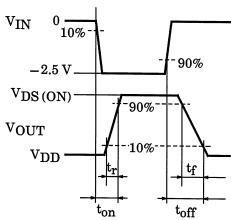


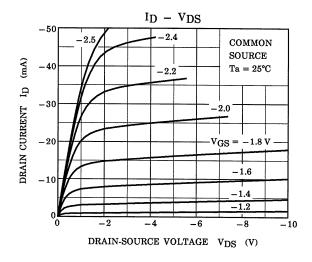


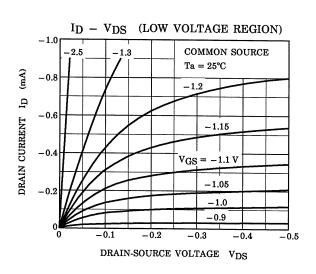
Q2 (Pch MOS FET)

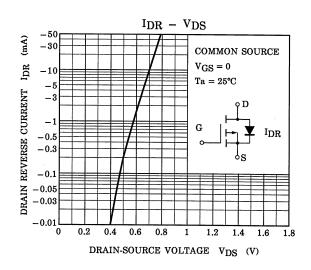
Switching Time Test Circuit

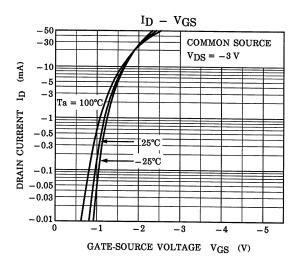




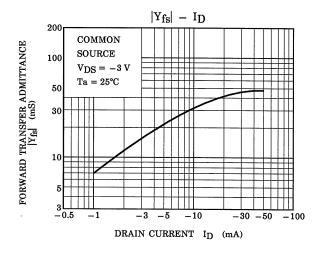


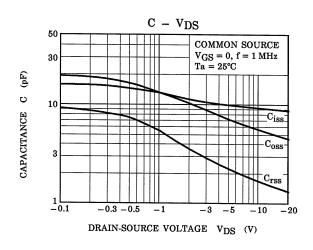


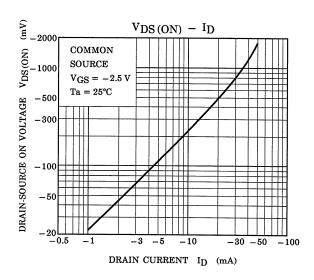


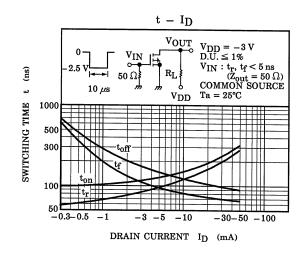


Q2 (Pch MOS FET)

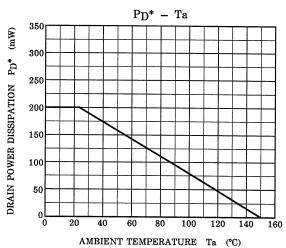








(Q1, Q2 common)



* : Total Rating

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20070701-EN GENERAL

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